

IN THE CLAIMS

1. (Currently amended) An optical transceiver module comprising:
a housing having disposed therein a transmitter and/or a receiver, wherein said housing further comprises a pair of ~~rails~~grooves disposed on opposite sides of said housing, said grooves ~~rails~~ having a plurality of spring-like fingers arranged to enable said module to be removably inserted into a suitably configured board.
2. (Currently amended) A module as claimed in ~~C~~claim 1, wherein electrical connection means are disposed at a back end of said module.
3. (Previously presented) A module as claimed in claim 1, wherein said housing includes a plurality of fins disposed thereon and arranged to facilitate temperature control of said module.
4. (Previously presented) A module as claimed in claim 1, wherein said module includes a bezel disposed at a front end of said module, said bezel having a pair of arms each extending from diagonally opposite corners of said bezel.
5. (Previously presented) A module as claimed in claim 1, wherein said housing comprises an upper half and a lower half sandwiched together, and an electrically conductive gasket disposed there between to facilitate electrical connection between said upper and lower halves.
6. (Currently amended) An optical transceiver system comprising:
an optical transceiver module including a housing having disposed therein a transmitter and/or a receiver, wherein said housing further includes a pair of grooves ~~rails~~ disposed on opposite sides of said housing, said grooves ~~rails~~ having a plurality of spring-like fingers arranged to enable said module to be removably inserted into a suitably configured board; ~~wherein said system further comprises~~ that is disposed in a chassis

~~having said suitably configured board disposed therein, and chassis electrical connector means arranged to receive said a module electrical connector means.~~

7. (Currently amended) A system as claimed in ~~C~~claim 6, wherein said suitably configured board is disposed within said chassis on a plurality of mounting means so as to enable air to pass both above and below said module.

8. (Currently amended) A system as claimed in claim 6, wherein said system further comprises shield means disposed substantially around said module and said ~~system-chassis~~ electrical connectors means so as to provide electrical connection from said module to said suitably configured board.

9. (Currently amended) A system as claimed in ~~C~~claim 8, wherein said shield means includes a plurality of resilient fingers arranged to exert pressure on said housing so as to improve electrical connection between said housing and said shield means.

10. (Previously presented) A system as claimed in claim 6, wherein a layer of electrically conductive material is disposed on said suitably configured board in an area substantially surrounding said module, so as to further improve electrical connection between said module and said chassis.

11. (Currently amended) A system as claimed in ~~C~~claim 10, wherein said layer of electrically conductive material is comprised of gold.

12. (Previously presented) A system as claimed in claim 7, wherein said module, said chassis and said suitably configured board are electrically grounded.

13. (Currently amended) An optical telecommunications network comprising:
an optical transceiver system ~~having~~comprising:

an optical transceiver module including a housing having disposed therein a transmitter and/or a receiver, wherein said housing further includes a pair of

~~grooves rails~~ disposed on opposite sides of said housing, said ~~grooves rails~~ having a plurality of spring-like fingers arranged to enable said module to be removably inserted into a suitably configured board; ~~that is disposed in wherein said system further comprises a chassis having said suitably configured board disposed therein, and chassis electrical connector means arranged to receive said a module electrical connector means.~~

14. (New) A network as claimed in claim 13, wherein said suitably configured board includes a structure that mates with said grooves, and wherein said spring-like fingers exert a force against said structure that is perpendicular to a longitudinal axis of said grooves.

15. (New) An optical transceiver as claimed in claim 1, wherein said suitably configured board includes a structure that mates with said grooves, and wherein said spring-like fingers exert a force against said structure that is perpendicular to a longitudinal axis of said grooves.

16. (New) An optical transceiver system as claimed in claim 6, wherein said suitably configured board includes a structure that mates with said grooves, and wherein said spring-like fingers exert a force against said structure that is perpendicular to a longitudinal axis of said grooves.